

## LTM4616 144LD 15mm X 15mm X 3.42mm (TABLE OF MATERIAL DECLARATION)

***The LTM4616 is RoHS compliant per EU RoHS Directive 2003/95/EC.***

It contains less than 100ppm cadmium (Cd) and less than 1,000ppm of each - lead (Pb), mercury (Hg), hexavalent chromium (Cr+), polybrominated biphenyl (PBB) and polybrominated diphenyl ether (PBDE)

No.	Part Name	Material Name	Component Weight (gram)	Materials Analysis (element)	CAS Number	Material Mass (gram)	Materials Analysis (weight %)
1	Substrate	Circuit Board	0.1650	Barium Compounds	7727-43-7	0.0024752	1.500
				Filler Substances (Silica Crystalline)	-	0.0658630	39.915
				Copper Metal	7440-50-8	0.0924056	56.000
				Copper Compounds	1328-53-6	0.0000297	0.018
				Ecotoxic substances	7439-92-1	0.0000000	0.000
				Gold metal or alloy	7440-57-5	0.0007590	0.460
				Nickel	7440-02-0	0.0034652	2.100
				Zinc	7440-66-6	0.0000116	0.007
2	Solder Paste	Alloy	0.0230	Sn	7440-31-5	0.0218025	95.000
				Sb	7440-36-0	0.0011475	5.000
3	Passive/Active Components		0.4688	Iron Powder (Fe)	7439-89-6	0.2119450	45.210
				Copper (Cu)	7440-50-8	0.1164260	24.835
				Nickel (Ni)	7440-02-0	0.0008670	0.185
				Tin (Sn)	7440-31-5	0.0004620	0.099
				Miscellaneous	-	0.1391000	29.672
4	Active Ics	Silicon	0.0124	Silicon	7440-21-3	0.0123610	100.000
5	Wire	Gold	0.0032	Au	7440-57-5	0.0032230	99.990
6	Encapsulation	Epoxy Resin	1.1051	Fused Silica	60676-86-0	0.8531372	77.200
				Epoxy Resin	-	0.0983539	8.900
				Phenol Resin	-	0.0983539	8.900
				Crytalline Silica	14808-60-7	0.0331530	3.000
				Carbon Black	1333-86-4	0.0055255	0.500
				Metal Hydroxide	-	0.0165765	1.500
7	Solder Ball		0.2234	Sn	7440-31-5	0.21562	96.50
				Ag	7440-22-4	0.00670	3.00
				Cu	7440-50-8	0.00112	0.50
Total Package Weight			2.0009				

Note: Composition derived from MSDS and material C of C from Vendors

Component Weight based on assembly of generic parts